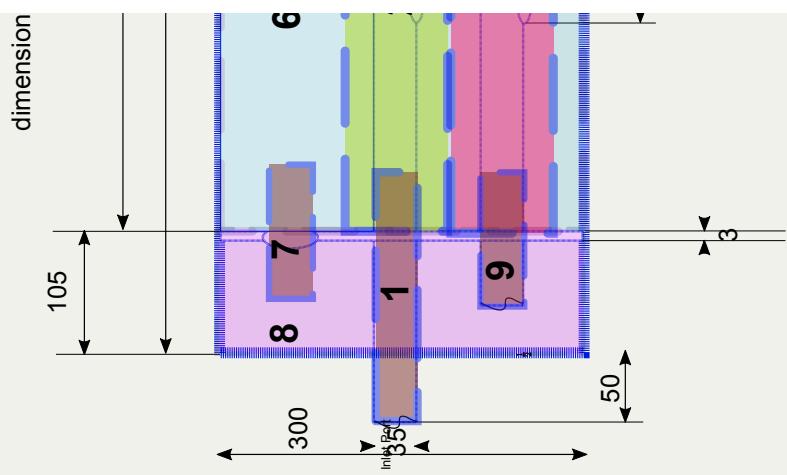


16

Siddab Co



## File Download Center

### Multichamber

Michael Raba, MSc Candidate

ANSYS Simulation

- File: Mark-I-MDF-cleaned-data.wbpx
- Created with: ANSYS 2023 R2
- [Download ANSYS File](#)

Sidlab and Ansys Fi

## Muffler System

ite at University of Kentucky

9-15 Mon 12:38

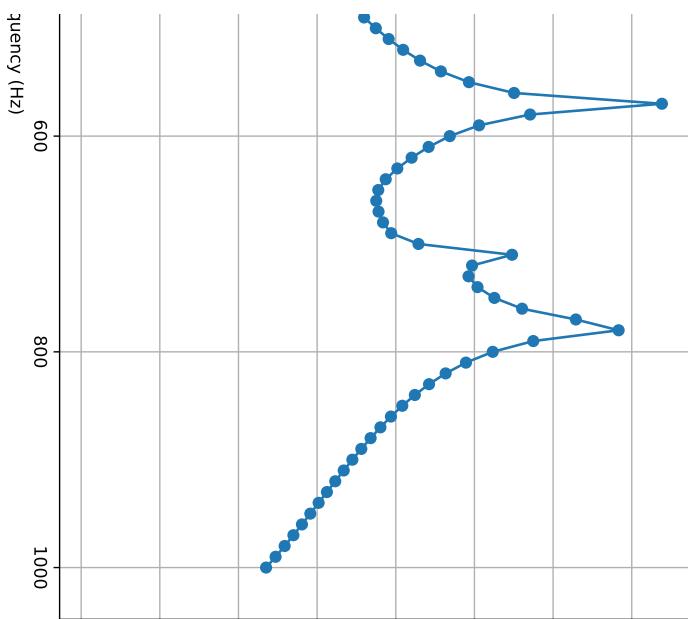
[SIDLAB Model](#)

- **File:** Mark3Sid.zip
- **Created with:** SIDLAB 5.1
- [\*\*Download SIDLAB File\*\*](#)

### Multicomponent Muffimulation

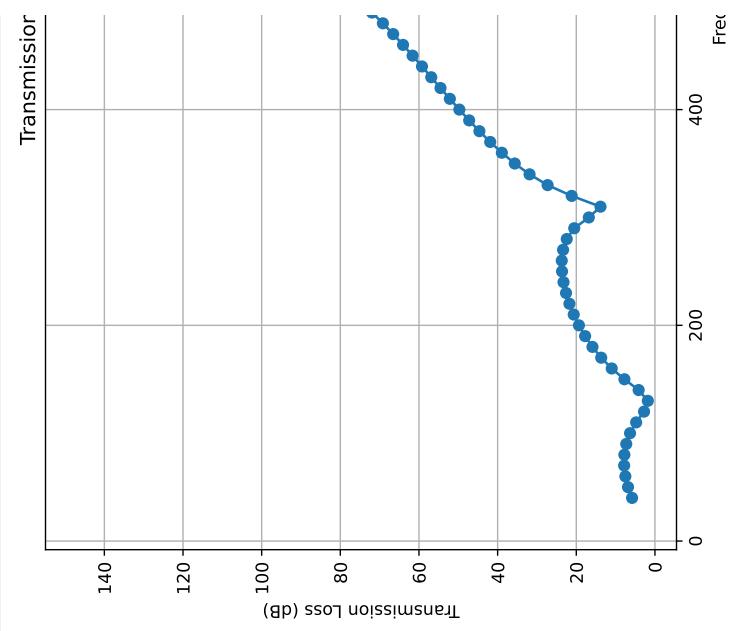
s (0–1000 Hz) Simlab model

Loss vs Frequency



### Simlab S<sup>3</sup>ler Internal Geometry

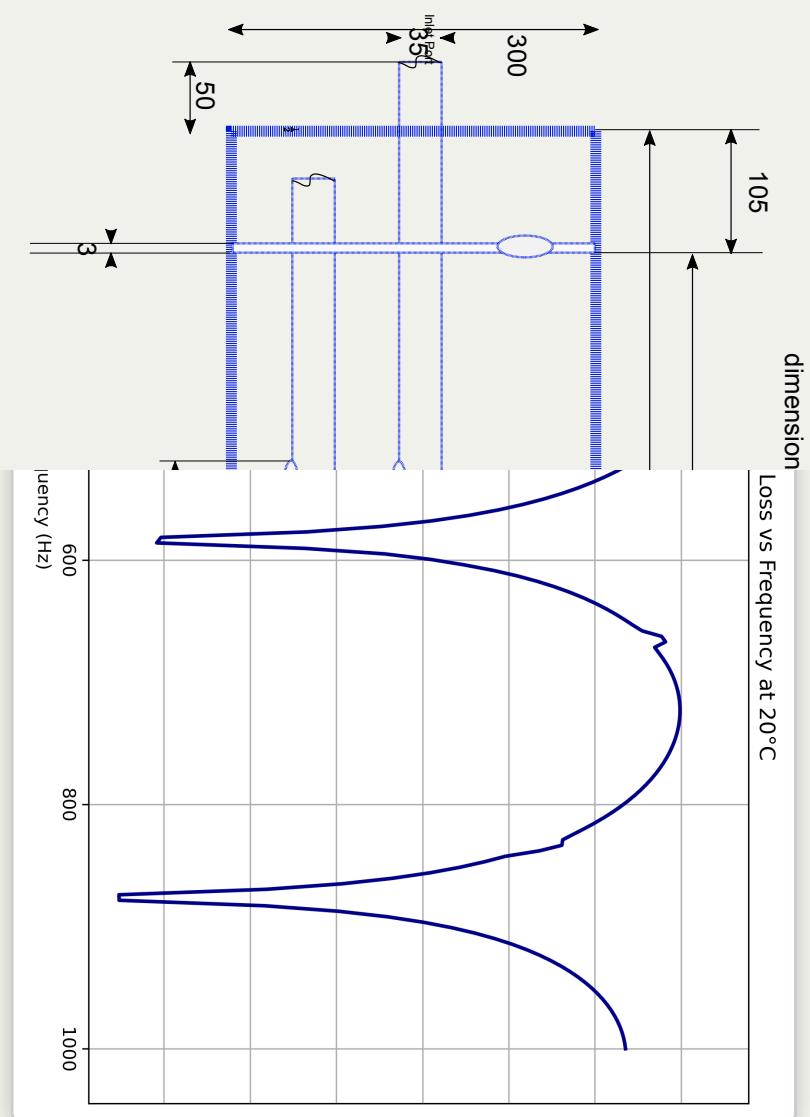
Simulated Transmission Loss



12

mulation

Dime<sup>approximating muffler walls as fluid at 20 deg C</sup>



6 Muffler between 5 Hz and 1000 Hz at 20°C.

Ansys Si

Simulated Transmission Loss (0–1000 Hz) by ε<sub>nsions</sub>

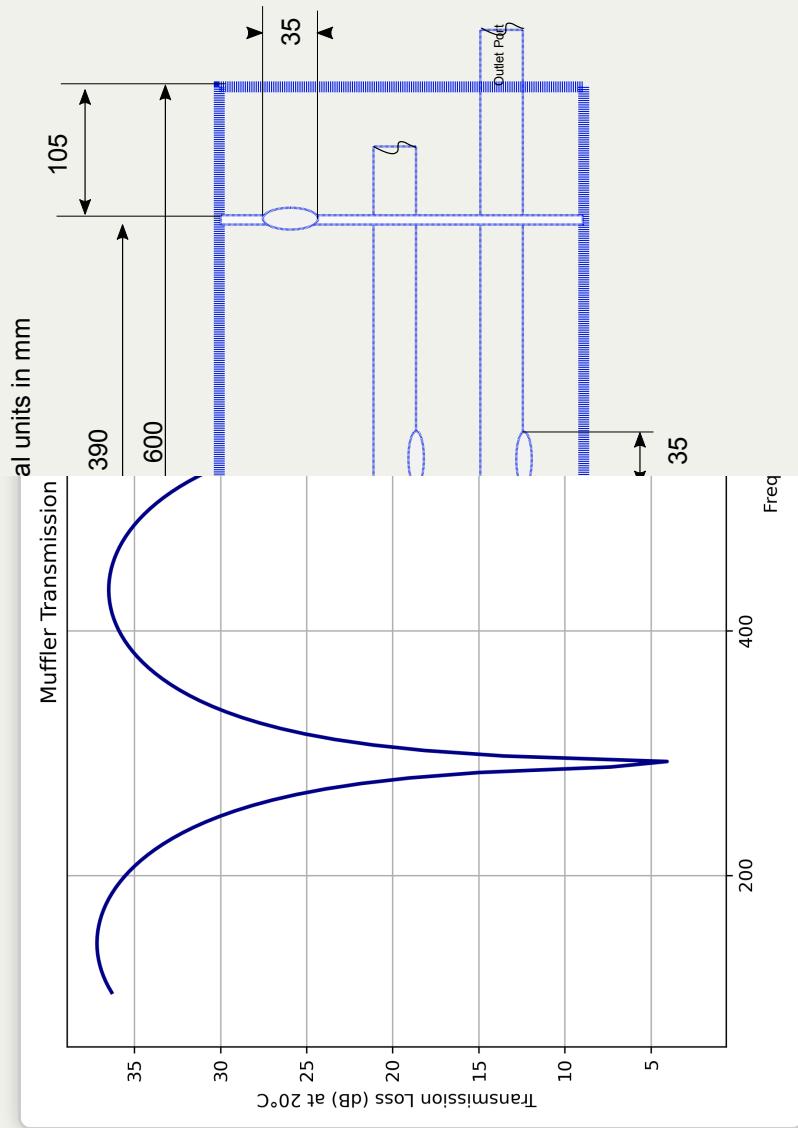
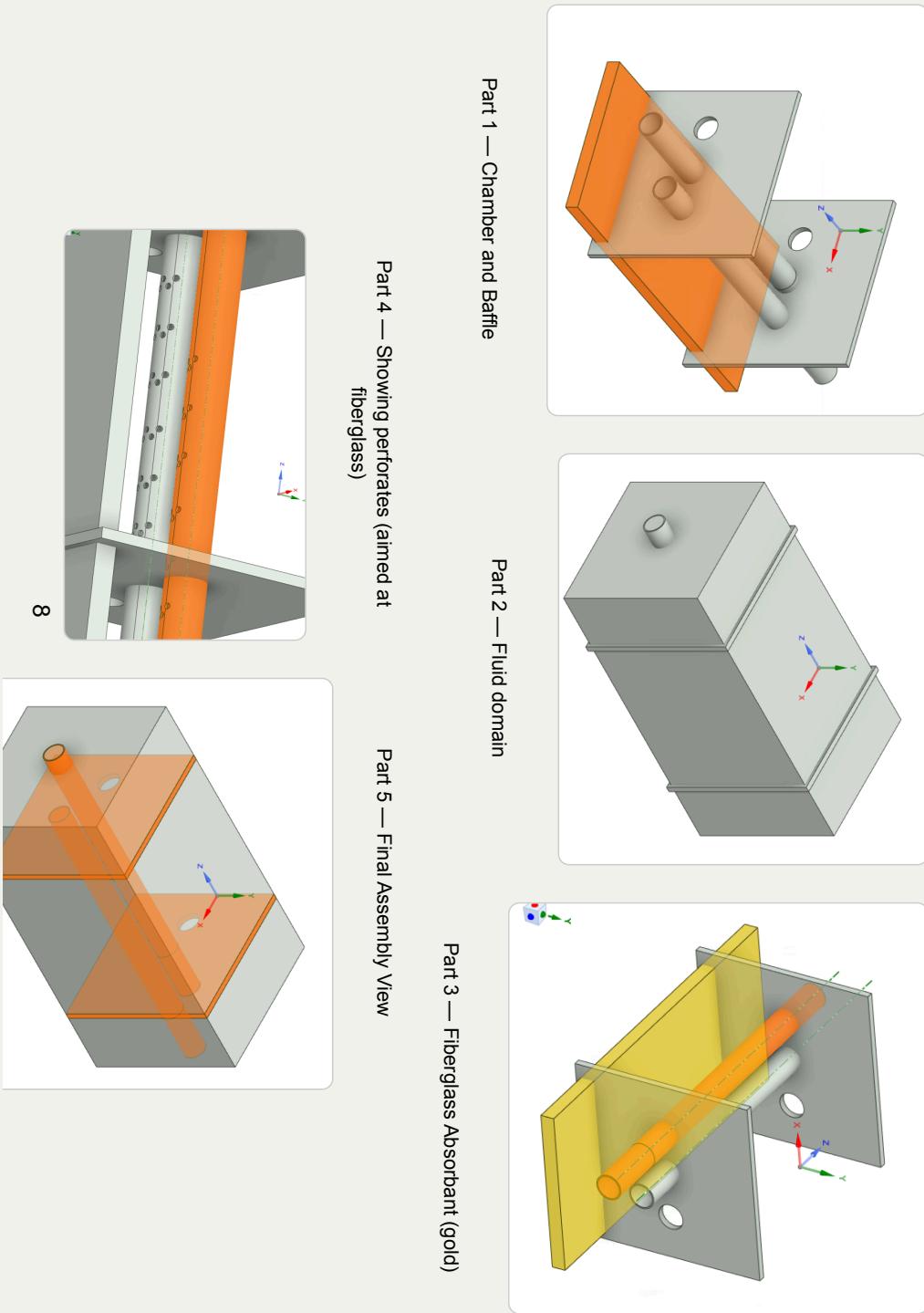
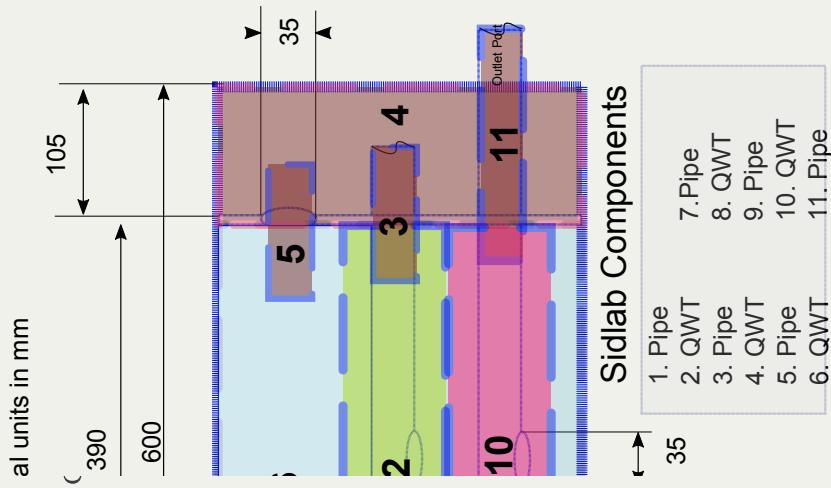


Figure: Transmission Loss curve of the m

## Schematic Variants for Muffler Subcomponents



ponents



#### Image Reference

Values are from correspond to 60Sn40Pb solder parameters used in Anand's model:

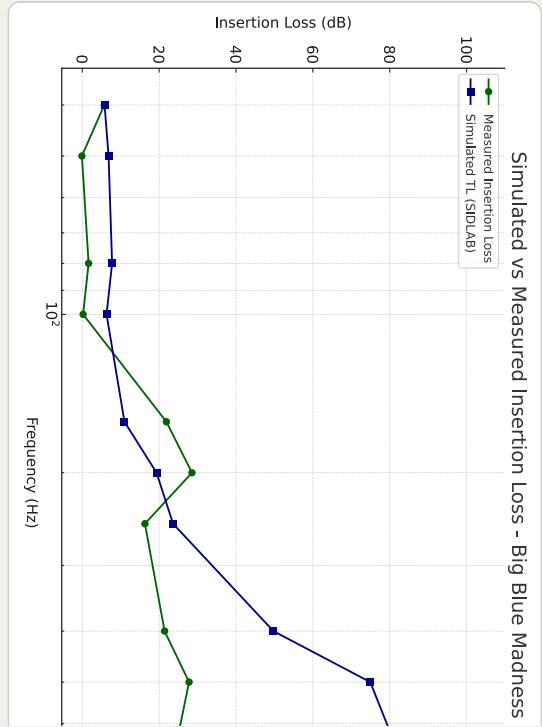
- $S_0$ : Initial deformation resistance
- $Q/R$ : Activation energy over gas constant
- $A$ : Pre-exponential factor for flow rate
- $\xi$ : Multiplier of stress inside sinh
- $m$ : Strain rate sensitivity of stress
- $h_0$ : Hardening/softening constant
- $\hat{s}$ : Coefficient for saturation stress
- $n$ : Strain rate sensitivity of saturation
- $a$ : Strain rate sensitivity of hardening or softening

32

17

## Simulated vs Measured-Type Viscoplastic Model

### Measured vs Simulated TL



### Evolution of Deformation Resistance $s$

- $\dot{s} = h_0 \left| 1 - \frac{s}{s^*} \right|^a \text{ sign} \left( 1 - \frac{s}{s^*} \right) \dot{\varepsilon}^p$
- Describes dynamic hardening and softening of the material.
- $s$  evolves depending on proximity to  $s^*$  and flow activity.

Note: Constants  $A, Q, m, j, h_0, \hat{s}, n, a$  are material-specific and fitted to experimental creep/strain rate data.

## Main Equations of Wang's Anured Insertion Loss

### Flow Rule (Plastic Strain Rate)

$$\dot{\varepsilon}^p = A \exp\left(-\frac{Q}{RT}\right) \left[ \sinh\left(\frac{j\sigma}{s}\right) \right]^{1/m}$$

- Plastic strain rate increases with stress and temperature.
- No explicit yield surface; flow occurs at all nonzero stresses.



### Deformation Resistance Saturation $s^*$

$$s^* = \hat{s} \left( \frac{\dot{\varepsilon}^p}{A} \exp\left(\frac{Q}{RT}\right) \right)^n$$

- Defines the steady-state value that  $s$  evolves toward.
- Depends on strain rate and temperature.

## Insertion Loss Explanation

Insertion Loss (IL) quantifies how much sound is attenuated when a muffler is added to the system.

### General formula:

$$IL = 10 \log_{10} \left( \frac{P_{\text{baseline}}}{P_{\text{muffler}}} \right)$$

Because our data is already in decibels (dB), this simplifies to:

$$IL = \text{Power}_{\text{baseline}} (\text{dB}) - \text{Power}_{\text{muffler}} (\text{dB})$$

editions at Two Strain Rates

### Key Insights from Wang (2001)

- “At lower strain rates, recovery dominates... the stress levels off early.”
- “At high strain rates, hardening dominates, and the stress grows continuously.”

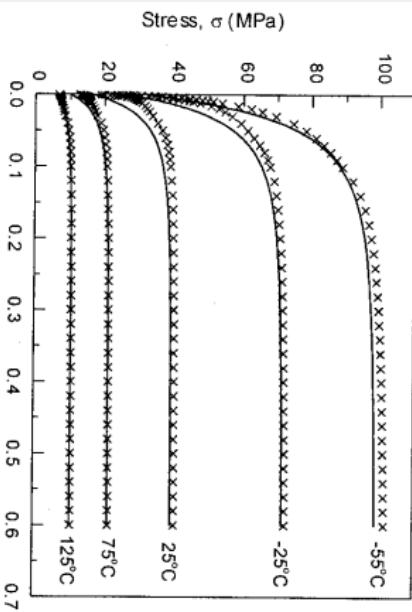
Refer

Cited

Anand's model smoothly captures strain-rate and temperature dependence of solder materials.

1. Munjai ML. *Acoustics of Ducts and Mufflers*. 2nd ed. V <https://doi.org/10.1002/9781118443125>
2. Dokumaci E. *Duct Acoustics: Fundamentals and Application*. Press; 2021. ISBN: 9781108840750. <https://doi.org/10>

**Note:** These references are foundational texts in muffler a schematic development, an



(b)  $\dot{\varepsilon} = 1.0 \times 10^{-4} \text{ s}^{-1}$

## Comparing Anand Model Predictions

### Observed Behavior

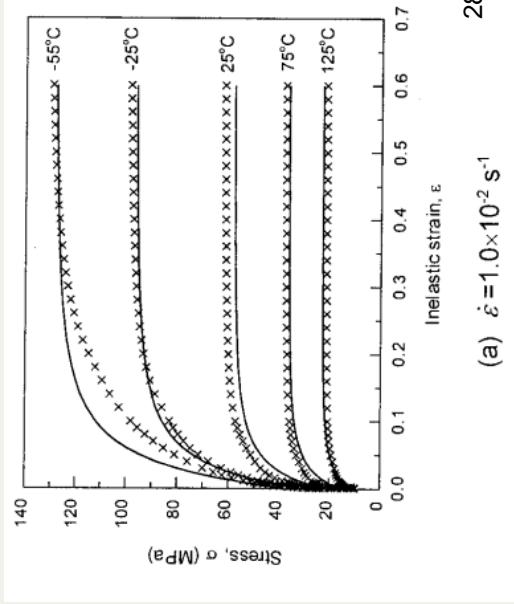
- **Top Graph (a):**  $\dot{\varepsilon} = 10^{-2} \text{ s}^{-1}$ 
  - High strain rate  $\rightarrow$  higher stress
  - Recovery negligible  $\rightarrow$  pronounced hardening
- **Bottom Graph (b):**  $\dot{\varepsilon} = 10^{-4} \text{ s}^{-1}$ 
  - Lower strain rate  $\rightarrow$  lower stress at same strain rates
  - Recovery and creep effects more significant

**Model Accuracy:** Lines = model prediction, X = experimental data

Viley; 2014. ISBN: 9781118443125.

*Cations to Mufflers and Silencers.* Cambridge University

.1017/9781108840750



nd duct acoustics and were consulted for system modeling,  
d transmission loss analysis.

001) Apply to Solder

### Why Wang's Paper Matters

Wang's unified viscoplastic framework to model solder behavior.  
Model can be reduced and fitted from experiments.  
The theory into engineering-scale implementation.  
Solder joints in microelectronic packages (chip on PCB, soldered

Anand Model: Viscoelastoplasticity).

Michael Raba, MSc Candidate

Created: 2025-0

(b)



Case Study: Wang (2)

Source: Wang, C. H. (2001). "A Unified Creep-Plasticity Model for Solder Alloys." [DOI: 10.1115/1.1371781](https://doi.org/10.1115/1.1371781)

- Applies Ar
  - Anand's m
  - transition t
  - Targets so



(a) Site at University of Kentucky

9-15 Mon 12:39

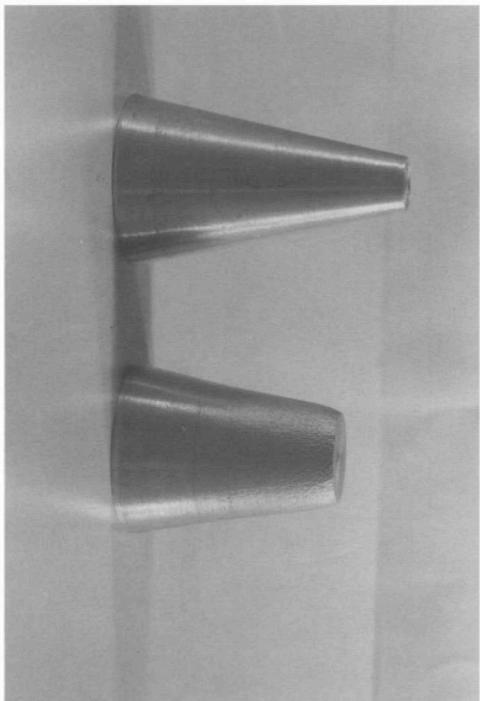
connector and its Application to Solder Joints

## Constitutive Equations for Hot-Working of Metals

**Author:** Lalit Anand (1985)

**DOI:** 10.1016/0749-6419(85)90004-X

One of the foundational papers in thermodynamically consistent viscoplasticity modeling—especially significant in the context of metals subjected to large strains and high temperatures.



**Fig. 25.** 1100 aluminum state gradient specimens before and after testing.

International Journal of Plasticity, Vol. 1, pp. 217-231, 1985  
Printed in the U.S.A.  
© 1985 Pergamon Press Ltd.

0749-6419(85)90004-X  
\$7.00

### CONSTITUTIVE EQUATIONS FOR HOT-WORKING OF METALS

LALIT ANAND  
Manufacturing Institute of Technology  
(Communicated by Theodor Lémann, Ruhr Universität Bochum)

**Abstract**— Elevated temperature deformation processing—"hot-working," is an important step during the manufacturing of most metal products. Central to any successful analysis of a hot-working process is the use of appropriate rate and temperature-dependent constitutive equations for large, interrupted infinitesimal deformations, which can faithfully account for strain-hardening, hot restoration processes of recovery and recrystallization and strain rate and temperature history effects. In this paper we develop a set of phenomenological, material variable-type constitutive equations describing the elevated temperature deformation of metals. We use a scalar and a symmetric, transversely, wave-like elastic tensor as internal variables. This allows a unique representation of the plastic behavior of metals. The effect of the different modes of microstructure evolution on the limits of recovery, and of isotropic materials. Special cases within the constitutive framework developed here which should be suitable for analyzing hot-working processes are indicated.

#### 1. INTRODUCTION

Hot-working is an important processing step during the manufacture of approximately more than eighty-five percent of all metal products. The main features of hot-working are that metals are deformed into the desired shapes at temperatures in the range of  $-0.5$  through  $-0.9 \times \delta_m$ , where  $\delta_m$  is the melting temperature in degrees Kelvin, and at strain rates in the range of  $-10^{-4}$  through  $-10^2$  sec $^{-1}$ . It is to be noted that most hot-working processes are more than mere shape-making operations; an important goal of hot-working is to subject the workpiece to appropriate thermo-mechanical processing histories which will produce microstructures that optimize the mechanical properties of the product.

The major quantities of metals and alloys are hot-worked under interrupted non-isothermal conditions. The principles of the physical metallurgy of such deformation processing are now well recognized (e.g., Jones *et al.* [1969], Suresh & McG Tegar [1972], McQuinn & Jonas [1975], and Stilzak [1978]). During a deformation pass, the stress is found to be a strong function of the strain rate, temperature, and the defect and microstructural state of the material. The strain-hardening produced by the deformation tends to be counteracted by dynamic recovery processes. These recovery processes result in a rearrangement and annihilation of dislocations in such a manner that as the strain in a pass increases, the dislocations tend to arrange themselves into sub-grain walls. In some metals and alloys (especially those with a high stacking fault energy, e.g., Al,  $\alpha$ -Fe and other ferritic alloys) dynamic recovery can balance strain-hardening and an apparent steady state stress level can be achieved and maintained to large strains before fracture occurs. In other metals and alloys in which recovery is less rapid especially those metals with low stacking fault energies, e.g., Ni,  $\gamma$ -Fe and other austenitic

## Relaxed Configuration

### Kinematics in the Relaxed Configuration

- Elastic deformation gradient:

$$F = F^e F^p \quad \Rightarrow \quad F^e = F F^{p-1}$$

- Elastic right Cauchy-Green tensor:

$$C^e = F^{eT} F^e$$

- Elastic Green–Lagrange strain tensor:

$$E^e = \frac{1}{2}(C^e - I)$$

### Numerical Values

- $S_0 = 5.633 \times 10^7 \text{ Pa}$
- $Q/R = 10830 \text{ K}$
- $A = 1.49 \times 10^7 \text{ s}^{-1}$
- $\zeta = 11$
- $m = 0.303$
- $h_0 = 2.6408 \times 10^9 \text{ Pa}$
- $\hat{s} = 8.042 \times 10^7 \text{ Pa}$
- $n = 0.0231$
- $a = 1.34$

### Sum

These constants match Wang's paper for modeling 60Sn40Pb viscoplasticity.

- Elastic kinematics and stress measures are formulate plastic and elastic contributions.
- Stress Power Split allows Anand to cleanly isolate plastic and elastic contributions.
- Green-Lagrange strain tensor  $E^e$  is used because it is more consistent with the relaxed configuration.
- The right Cauchy-Green tensor  $C^e = F^{eT} F^e$  is required to calculate the plastic strain rate  $\dot{E}^e$ .
- The deformation gradient  $F^e$  without referencing spatial coordinates is used to calculate the plastic strain rate  $\dot{E}^e$ .

Forward Euler Explicit time integration

#### Initialization

- Material constants:  $A, Q/R, j, m, h_0, \hat{s}, n, \alpha, E$
- Strain rate:  $\dot{\varepsilon}$
- Temperature set:  $\{T_i\}$
- Set:  $\varepsilon^p(0) = 0, s(0) = \hat{s}$

#### Time Evolution Loop

1.  $\varepsilon_{\text{total}}(t) = \dot{\varepsilon}t$
2.  $\sigma_{\text{trial}} = E(\varepsilon_{\text{total}} - \varepsilon^p)$
3. Compute  $x = \frac{j\sigma}{s}$
4. Approximate  $\sinh(x)$  (linearize if  $|x| \ll 1$ )
5.  $\dot{\varepsilon}^p = A e^{-Q/RT} (\sinh(x))^{1/m}$

iate) Configuration

What Happens in the Relaxed Configuration?

- The elastic deformation gradient  $F^e$  is measured from the relaxed state to the current deformed state.
- Elastic strain measures like  $C^e$  and  $E^e$  are defined in this configuration.
- The Kirchhoff stress  $\tilde{\mathbf{T}}$  is naturally associated with the relaxed volume.
- Plastic flow is accounted for separately through the plastic velocity gradient  $\mathbf{L}^p$ .

mary:

cleanly, enabling proper definition of thermodynamics and

## Integration scheme Pseudocode

### Relaxed (Intermed)

#### Context for the Relaxed Configuration

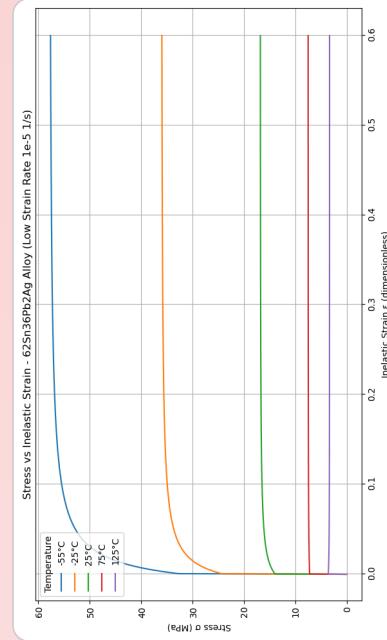
- The relaxed configuration represents the material after removing plastic deformations but before applying new elastic deformations.
- It is introduced to separate permanent plastic effects from recoverable elastic effects.
- All thermodynamic potentials, internal variables, and evolution laws are defined relative to this frame.
- The relaxed state provides a clean, natural reference for measuring elastic strain  $E^e$  and computing dissipation.

### Plastic Flow & Resistance Evolution

6.  $s^* = \hat{s} \left( \frac{\dot{\varepsilon}^p}{A} e^{Q/RT} \right)^n$
7.  $\dot{s} = h_0 \left| 1 - \frac{s}{s^*} \right|^a \text{sign} \left( 1 - \frac{s}{s^*} \right) \dot{\varepsilon}^p$
8. Update:  $\varepsilon^p(t + \Delta t) = \varepsilon^p(t) + \dot{\varepsilon}^p \Delta t$
9. Update:  $s(t + \Delta t) = s(t) + \dot{s} \Delta t$
10. Record  $(\varepsilon_{\text{total}}, \sigma_{\text{trial}})$

#### Termination

- Stop when  $\dot{\varepsilon}_{\text{total}} \geq \dot{\varepsilon}_{\text{max}}$
- Plot  $\sigma$  vs  $\varepsilon$  for all  $T_i$



### Sum

- The relaxed configuration isolates elastic responses from plastic evolution laws.

## 1d Thermal Effects

### Forward Euler Scheme

- Thermal expansion creates strain even without external forces.
- Without subtracting  $\Pi\theta$ , the model would falsely attribute thermal strain as mechanical stress.
- Subtracting isolates the true mechanical response from thermal effects.

```

import numpy as np
import matplotlib.pyplot as plt
from scipy.integrate import solve_ivp

# Material constants for 62Sn37Pb2Ag solder alloy
A = 2.24e8                                # 1/s
Q_R = 11200                                 # K
j = 13                                     # dimensionless
m = 0.21                                    # dimensionless
h0 = 1.62e10                                # Pa
s0 = 8.47e7                                  # Pa
s_hat = 8.47e7                               # Pa
n = 0.0277                                   # dimensionless
a = 1.7                                      # dimensionless
E = 5.2e10                                   # Pa (Elastic modulus)

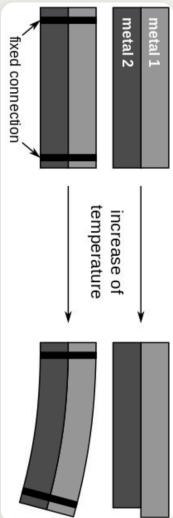
# Temperatures in Kelvin
T_C = [-55, -25, 25, 75, 125]
T_List = [T + 273.15 for T in T_C]

# Simulation parameters
strain_rate = 1e-5 # 1/s
eps_total_max = 0.6
t_max = eps_total_max / strain_rate
time_steps = 10000
t_eval = np.linspace(0, t_max, time_steps)

# Define the ODE system
def system(t, y, T):
    ep_p, s = y
    ep_p_dot = y[0]
    s_dot = y[1]
    sigma_total = E * (eps_p_total - ep_p)
    sigma_trail = E * (eps_p_total - ep_p)
    x = j * sigma_trail / s
    if np.abs(x) < 0.01:
        s_sim_K = x
    else:
        s_sim_K = np.sinh(np.cosh(s, -30, 30))
    sinh_x = np.sinh(np.cosh(s, -30, 30))
    dep_p_dot = A * np.maximum(sinh_x, 1e-12)
    s_star = s_hat * (dep_p / A * np.exp(Q_R / T))**n
    ds = h0 * np.abs((1 - s/s_star)**a * np.sign(j - s/s_star)) * dep_p
    return [dep_p_dot, ds]

# Plotting

```



### Why Subtract the Thermal Term?

rain without force.  
mechanical strains generate stresses.  
del physically accurate during heating and cooling.

## Stress Evolution and Thermal Effects

Stress Evolution at

ne for Anand Model

In the stress evolution equation,

$$\nabla \dot{\mathbf{T}} = \mathbb{L} [\mathbf{D} - \mathbf{D}^p] - \Pi \dot{\theta},$$

the term  $\Pi \dot{\theta}$  represents the stress change that would occur due to pure thermal expansion alone, without any mechanical loading.

- Thermal expansion induces stress
- Subtracting  $\Pi \dot{\theta}$  ensures only mechanical loading
- This keeps the constitutive model consistent

**Summary:**

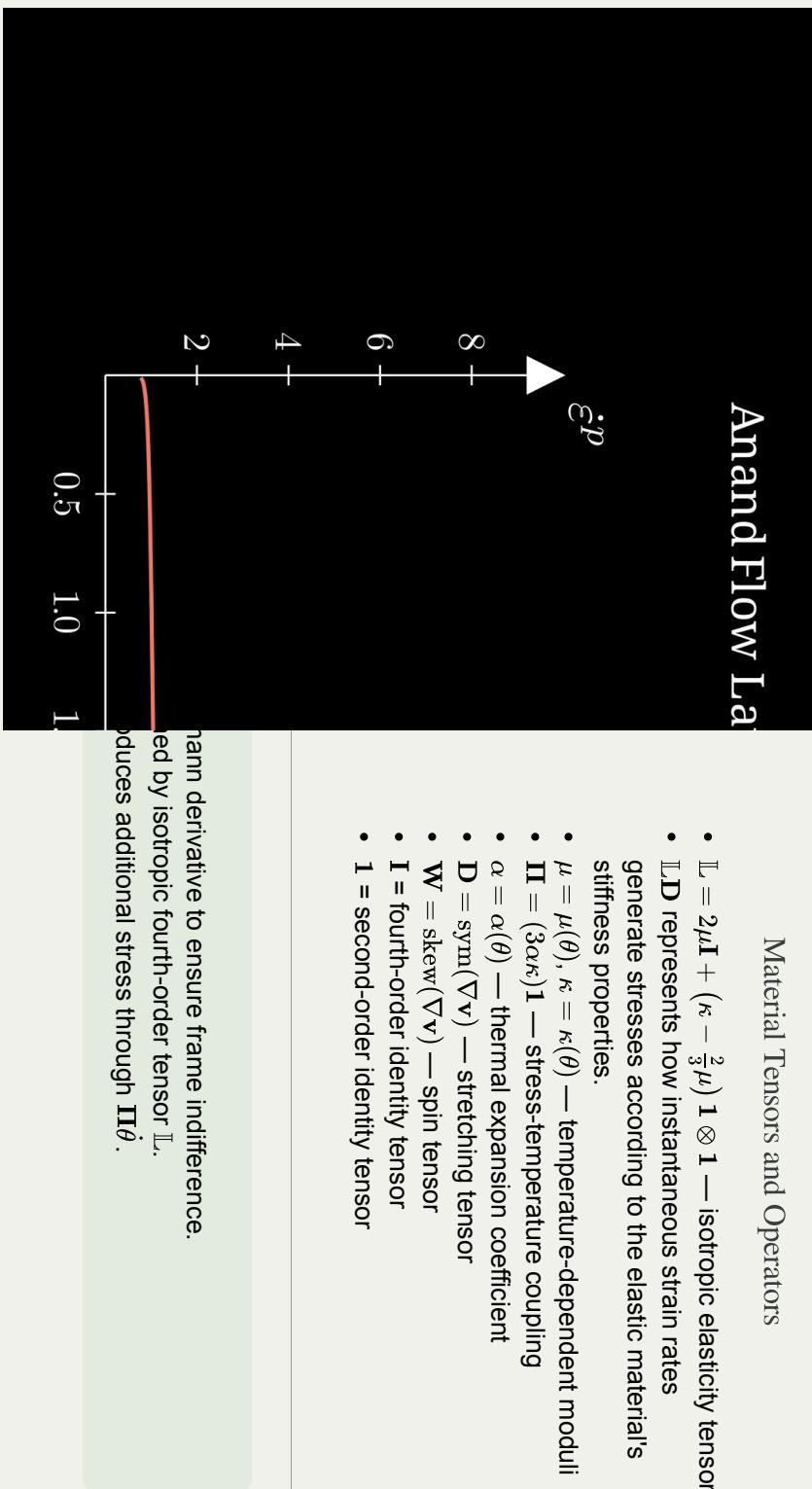
## Strain rate sensit

- As  $m \rightarrow 0$ , rate insensitive
- As  $m \rightarrow 1$ , small stress change for the Stress

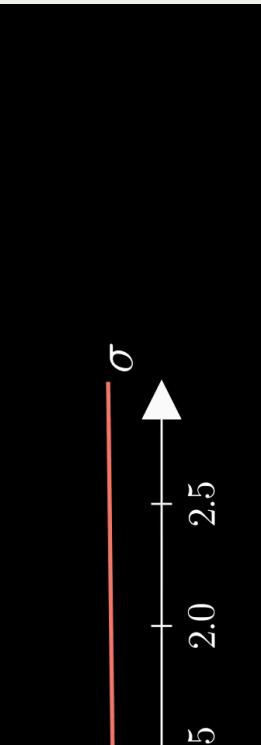
## Anand Flow Law

### Material Tensors and Operators

- $\mathbb{L} = 2\mu\mathbf{I} + (\kappa - \frac{2}{3}\mu)\mathbf{1} \otimes \mathbf{1}$  — isotropic elasticity tensor
- $\mathbb{LD}$  represents how instantaneous strain rates generate stresses according to the elastic material's stiffness properties.
- $\mu = \mu(\theta)$ ,  $\kappa = \kappa(\theta)$  — temperature-dependent moduli
- $\Pi = (3\alpha\kappa)\mathbf{1}$  — stress-temperature coupling
- $\alpha = \alpha(\theta)$  — thermal expansion coefficient
- $\mathbf{D} = \text{sym}(\nabla\mathbf{v})$  — stretching tensor
- $\mathbf{W} = \text{skew}(\nabla\mathbf{v})$  — spin tensor
- $\mathbf{I}$  = fourth-order identity tensor
- $\mathbf{1}$  = second-order identity tensor



Anand derivative to ensure frame indifference.  
ed by isotropic fourth-order tensor  $\mathbb{L}$ .  
duces additional stress through  $\Pi\dot{\theta}$ .



- Summary:**
- Stress rate follows Jaumann
  - Elastic response governs
  - Thermal expansion introduced

$$\overset{\nabla}{\dot{\mathbf{T}}} = \dot{\mathbf{T}} - \mathbf{W}\mathbf{T} + \mathbf{T}\mathbf{W}$$

Jaumann Rate Definition

(rate-form Hooke's law for finite deformation plasticity, with frame-indifference enforced through the Jaumann rate.)

$$\overset{\nabla}{\mathbf{T}} = \mathbb{L}[\mathbf{D} - \mathbf{D}^p] - \Pi\dot{\theta}$$

Stress Evolution Equation (Rate form of Hooke's Law)

Evolution Equation (yield)  
big change in strain rate causes big change in stress

## W: Varying \$m\$

$$m = 0.06$$

Flow rule

Tensorial Flow Rule (directional form)

$$\mathbf{D}^p = \dot{\epsilon}^p \left( \frac{3}{2} \frac{\mathbf{T}'}{\bar{\sigma}} \right)$$

Equivalent Stress Definition

$$\bar{\sigma} = \sqrt{\frac{3}{2} \mathbf{T}' : \mathbf{T}'}$$

Full Flow Rule with Hyperbolic Sine

$$\begin{aligned} \mathbf{D}^p &= A \exp\left(-\frac{Q}{R\theta}\right) \left[ \sinh\left(\xi \frac{\bar{\sigma}}{s}\right) \right]^{1/m} \left( \frac{3}{2} \frac{\mathbf{T}'}{\bar{\sigma}} \right), \\ &= \dot{\gamma}^p \left( \frac{\tilde{\mathbf{T}}'}{2\bar{\tau}} \right), \quad \bar{\tau} = \left\{ \frac{1}{2} \text{tr}(\tilde{\mathbf{T}}'^2) \right\}^{1/2} \end{aligned}$$

Plastic Strain Rate (magnitude form)

$$\dot{\epsilon}^p = A \exp\left(-\frac{Q}{R\theta}\right) \left[ \sinh\left(\xi \frac{\bar{\sigma}}{s}\right) \right]^{1/m}$$

- Direction given by  $\mathbf{T}'$ .
- Magnitude determined by hyperbolic sine based on  $\bar{\sigma}/s$ .
- $\bar{\tau}$  represents the effective shear stress computed from deviatoric stress.
- $\bar{\sigma} = \sqrt{\frac{3}{2} \mathbf{T}' : \mathbf{T}'}$  is the von Mises Equivalent stress, but is formally defined without yield point

**Summary:**

- Full flow = direction  $\times$  magnitude.

## Stress and Power Quantities

- Kirchhoff stress (weighted Cauchy stress):

$$\tilde{\mathbf{T}} = (\det F) \mathbf{T}$$

- Stress power split:

$$\dot{\omega} = \dot{\omega}^e + \dot{\omega}^p$$

$$\dot{\omega}^e = \tilde{\mathbf{T}} : \tilde{E}^e \quad , \quad \dot{\omega}^p = (C^e \tilde{\mathbf{T}}) : \mathbf{L}^p$$

### 1.3. Import

pipe = Pipe(); creates a Pipe Class. As the function

1. obj.CaseId - stores properties like Re, rotation number  $S$ , experiment frequently called vectors (rMat  $r = 1, \dots, 0.5$ )
2. obj.pod - eigen data, used for calculating POD
3. obj.solution - computed POD modes
4. obj.plt - plot configuration

**mary:**

ed relative to the relaxed configuration, cleanly separating  
astic dissipation from elastic storage.  
symmetrically captures nonlinear elastic strain relative to the  
red as an intermediate to compute  $E^e$  from the elastic  
ordinates

### Thermodynamic Separation

#### 1. Start with Total Dissipation:

$$\mathcal{D} = \dot{\omega} - \dot{\psi} \geq 0$$

$$\text{where } \dot{\omega} = \hat{\mathbf{T}} : \dot{\mathbf{E}}^e + (\mathbf{C}^e \hat{\mathbf{T}}) : \mathbf{L}^p$$

#### 2. Split Stress Power:

$$\dot{\omega} = \dot{\omega}^e + \dot{\omega}^p$$

with:

- $\dot{\omega}^e = \hat{\mathbf{T}} : \dot{\mathbf{E}}^e$
- $\dot{\omega}^p = (\mathbf{C}^e \hat{\mathbf{T}}) : \mathbf{L}^p$

#### 3. Group Terms with $\dot{\psi}$ :

$$(\dot{\omega}^e - \dot{\psi}) + \dot{\omega}^p \geq 0$$

#### 4. Apply Elastic Energy Consistency:

$$\dot{\omega}^e - \dot{\psi} = 0 \Rightarrow \dot{\omega}^p \geq 0$$

gge between  $\alpha\Phi$ ) according to Papers (Citriniti George 2000 for Classic POD,

dial graph)

### Key Physical Insights

- **Elastic deformations** are recoverable and do not cause entropy production.
- **All dissipation** stems from the plastic flow:  $\dot{\omega}^p$ .
- **Plastic work** increases entropy and governs viscoplastic evolution.

### 1.2. L<sub>c</sub>

1.  $\hookrightarrow$  initPod.m
  - carries out POD calculations (quadrature, multiplication Hellstrom Smits 2017 for Snapshot POD)
2.  $\hookrightarrow$  timeReconstructFlow.m
  - performs 2d reconstruction + plotSkmr (generates 1d ra

### Summary:

The stress power split ensures that the second law is satisfied by assigning dissipation solely to irreversible processes.

## Reference C

### Framework in the Reference Configuration

- The free energy  $\psi$  is defined relative to the reference configuration.
- State variables like  $E^e, \theta, \bar{g}, \bar{\mathbf{B}}, s$  are used as arguments of  $\psi$ .
- Stress is expressed using the second Piola–Kirchhoff tensor  $\mathbf{S}$ .
- Dissipation inequality, stress–strain relations, and evolution laws are all written in reference variables.
- Mass density  $\rho_0$  from the reference configuration normalizes all terms.

.ayout

in binary files, takes eg m-fft

corrMat, finds eigenvalues

## Sum

- In the reference configuration, all energy storage, str with reference-frame quantities for consistency and c

onfiguration

### Key Equations in the Reference Frame

- Free energy:

$$\boxed{\psi = \psi(E^e, \theta, \bar{g}, \bar{\mathbf{B}}, s)}$$

- Dissipation inequality:

$$\boxed{\dot{\psi} + \eta\dot{\theta} - \rho_0^{-1}\mathbf{S} : \dot{\mathbf{E}} + (\rho_0\theta)^{-1}\mathbf{q}_0 \cdot \mathbf{g}_0 \leq 0}$$

- Constitutive relation:

$$\boxed{\mathbf{S} = \rho_0 \frac{\partial \psi}{\partial E^e}}$$

1. b7.m
2. initSpectral.m
  - reads |
3.  $\hookrightarrow$  initEigs.m
  - forms

many:

ass updates, and internal variable evolution are formulated objectivity.

## Thermodynamic Quantities

- Free energy density:

$$\boxed{\psi = \epsilon - \theta\eta}$$

- Reduced dissipation inequality:

$$\boxed{\dot{\psi} + \eta\dot{\theta} - \rho^{-1}\mathbf{T} : \mathbf{L} + (\rho\theta)^{-1}\mathbf{q} \cdot \mathbf{g} \leq 0}$$

- State variables:

$$\{E^e, \theta, \bar{g}, \bar{\mathbf{B}}, s\}$$

with  $E^e$  as elastic strain and  $s$  as internal resistance.

## ion and Layout

- Free energy and dissipation
- Stress power naturally split
- Kirchhoff stress simplifies stress

**Summary:**

- Stress power per relaxed volume:

$$\dot{\omega} = \left( \frac{\rho_0}{\rho} \right) \mathbf{T} : \mathbf{L}$$

- Weighted Cauchy (Kirchhoff) stress:

$$\tilde{\mathbf{T}} = (\det F) \mathbf{T} \quad \text{or} \quad \tilde{\mathbf{T}} = \left( \frac{\rho_0}{\rho} \right) \mathbf{T}$$

- Decomposition of stress power:

$$\dot{\omega} = \dot{\omega}^e + \dot{\omega}^p$$

$$\dot{\omega}^e = \tilde{\mathbf{T}} : \dot{\mathbf{E}}^e, \quad \dot{\omega}^p = (C^e \tilde{\mathbf{T}}) : \mathbf{L}^p$$

### 1. Code Execut

1 govern thermodynamic consistency.  
s into elastic and plastic parts.  
stress evolution accounting for volume changes.

# POD Analysis of Turbulent Pipe Flow

M. Raba

Created: 2025-09-15 Mon 12:39

### 3.1. 4 D<sub>i</sub>

Exchange the order of summation and

$$\sum_l \Phi_T^{(l)}(k; m; r) \left( \frac{1}{\tau} \int_0^\tau \alpha^{(l)}_{\text{int Switches}} \right)$$

Due to the orthogonality, namely tns (above) are called, data is stored in sub-structs:

$\langle a^{(n)} \alpha^{(p)} \rangle$ : al flags such as quadrature (simpson/trapezoidal), number of gridpoints,

all terms where  $l \neq n$  will vanish, an

$$\Phi_T^{(n)}(k; m; r) \left( \frac{1}{\tau} \int_0^\tau \alpha_T^{(n)} \right)$$

This derivation assumes the normalization of nodes and their orthogonality,  
form that reveals the spatial structure ( $\Phi_T^{(n)}$ ).

ivation

uation, consider the integral:

2. Equations Used     $t) \alpha^{(n)*} (k; m_i; t) dt.$

ith its expansion:

$$\left. \right) \alpha^{(n)*} (k; m_i; t) dt.$$

### 3. Der

To derive the questioned eq

$$\frac{1}{\tau} \int_0^\tau \mathbf{u}_T(k; m; r, \text{in}) \text{ Code Procedure}$$

Substitute  $\mathbf{u}_T$  w

$$\frac{1}{\tau} \int_0^\tau \left( \sum_l \Phi_T^{(l)}(k; m; r) \alpha^{(l)}$$

## 2.1. Classic P

The following equations a

nstruction

$$\int_{r'} \mathbf{S}(k; m; r, r') \Phi^{(n)}(k; m; r') \quad \text{his is incorrect. The necessary use of (factor } \gamma \text{) is incorrect}$$

$$\mathbf{S}(k; m; r, r') = \lim_{\tau \rightarrow \infty} \frac{1}{\tau} \int_0^\tau \mathbf{u}(k$$

$$\alpha^{(n)}(k; m; t) = \int_r \mathbf{u}(k; m; r, t) \mathrm{d}$$

### OD Equations

re used in the above code.

#### 2.5. Reco

In order to reconstruct in code, caseId.fluctuation = 'off'. T

$$r' dr' = \lambda^{(n)}(k; m) \Phi^{(n)}(k; m; r)$$

$$; m; r, t) \mathbf{u}^*(k; m; r', t) dt$$

$$\lambda^{(n)*}(k; m; r) r dr$$

instruction

2.2. Classic POD  
tion is given by

$$\begin{aligned}
 & \int_{r'} \underbrace{r^{1/2} S_{i,j}(r, r'; m; f) r'^l}_{W_{i,j}(r, r'; m; f)} \Rightarrow \\
 & = \lambda^{(n)}(m, f) \underbrace{r^{1/2} \phi_i^{(n)}(r; \sum_{n=1} \sum_{m=0} \alpha^{(n)}(m; t) \Phi^{(n)}(r; m; x))}_{\hat{\lambda}^{(n)}(m; f) \hat{\phi}_i^{(n)}(r; m; x)} \\
 & \alpha_n(m; t) = \int_r \mathbf{u}(m; r; t)_i : \gamma \sum_{n=1} \sum_{m=0} \alpha^{(n)}(m; t) \Phi^{(n)}(r; m; x) \\
 & \text{construction can only be recovered by writing for factor } \gg 0.
 \end{aligned}$$

#### 2.4. Reco

The reconstruc Equations (Fixed)

$$q(\xi, t) - \bar{q}(\xi) \approx \sum_{j=1}^r a_j(t) \varphi_j(\xi) \underbrace{\phi_j^{*(n)}(r'; m; f) r'^{1/2} dr'}_{\phi_j^{*(n)}(r'; m; f)}$$

$$q(r, \theta, t; x) = \bar{q}(r, \theta, t; x) + \underbrace{m; f}_{f}$$

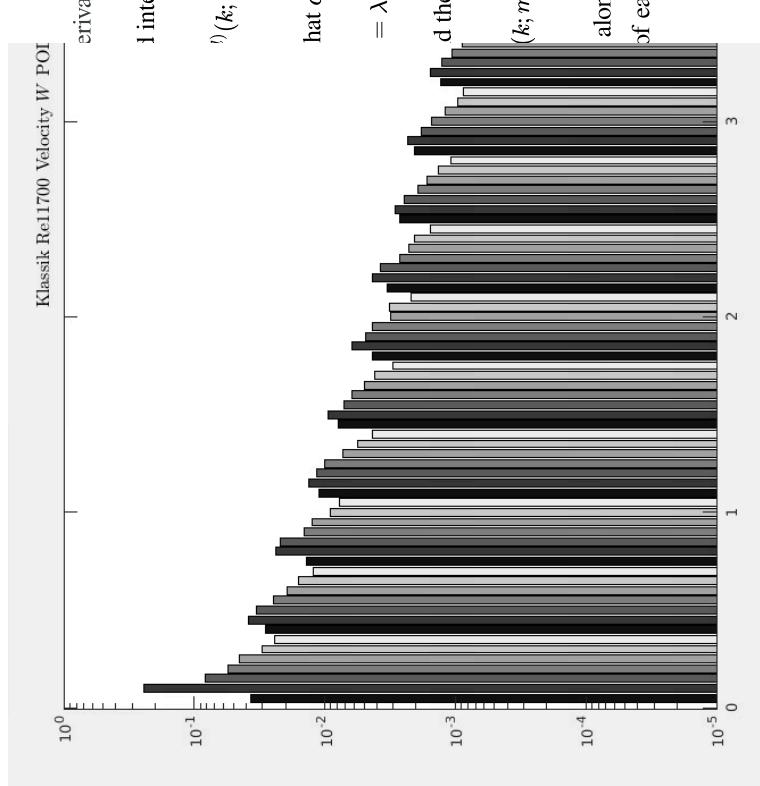
Since the snapshot pod implementation is not error-free, the re  $r'^{1/2} \Phi_n^*(m; r) dr$

$$q(r, \theta, t; x) = \bar{q}(r, \theta, t; x) + \text{(factor)}$$

### 2.3. Snapshot POD Equations

$$\begin{aligned}
& \lim_{\tau \rightarrow \infty} \frac{1}{\tau} \int_0^\tau \mathbf{u}_T(k; m, r, t) \alpha^{(n)*}(k; m; t) dt \\
&= \Phi_T^{(n)}(k; m; r) \lambda^{(n)}(k; m) \\
\mathbf{R}(k; m; t, t') &= \int_r \mathbf{u}(k; m; r, t) \mathbf{u}^*(k; m; r, t') r dr \\
&\lim_{\tau \rightarrow \infty} \frac{1}{\tau} \int_0^\tau \mathbf{u}_T(k; m, r, t) \alpha^{(n)*}(k; m; t) dt \\
&= \Phi_T^{(n)}(k; m; r) \lambda^{(n)}(k; m).
\end{aligned}$$

### 5.1. n=3



$\lambda=0$  Classic

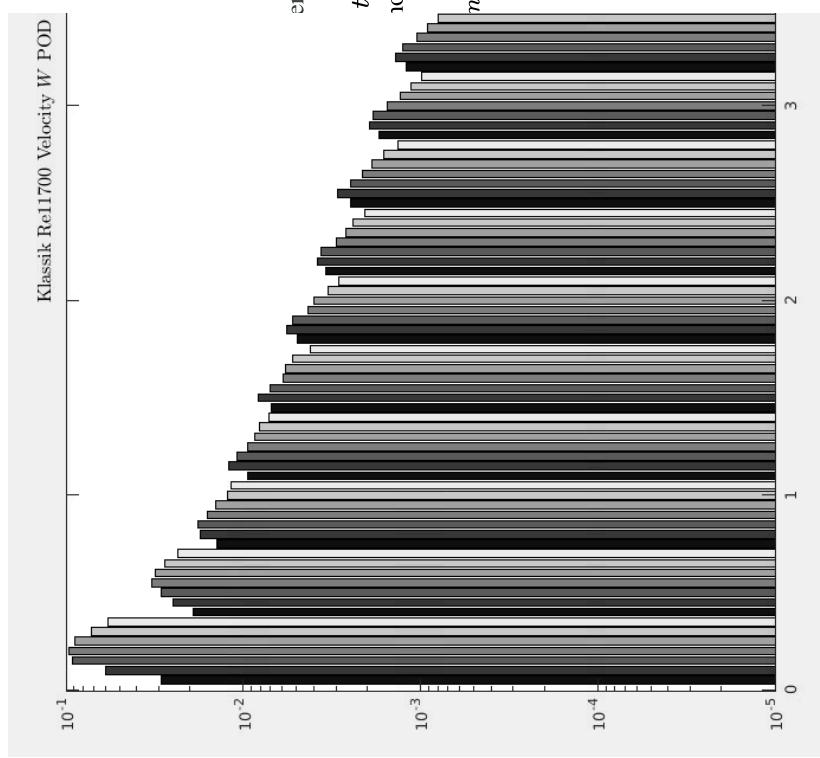


### 3.2. 6 D

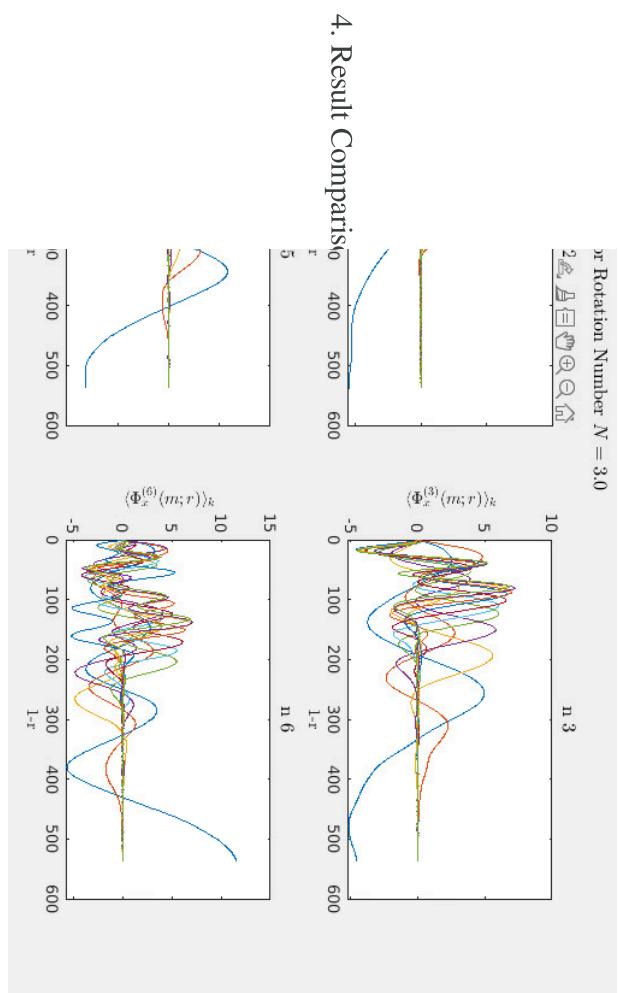
The cross-correlation tensor  $\mathbf{R}$  is defined as  $\mathbf{R}(k; m; t, t') = \int_r \mathbf{u}(k; m; r, [t \times t'])$  tensor. The  $n$  POD n

$$\lim_{\tau \rightarrow \infty} \frac{1}{\tau} \int_0^\tau \mathbf{u}_T(k; m; r, t) \alpha^{(n)*}(k; r)$$

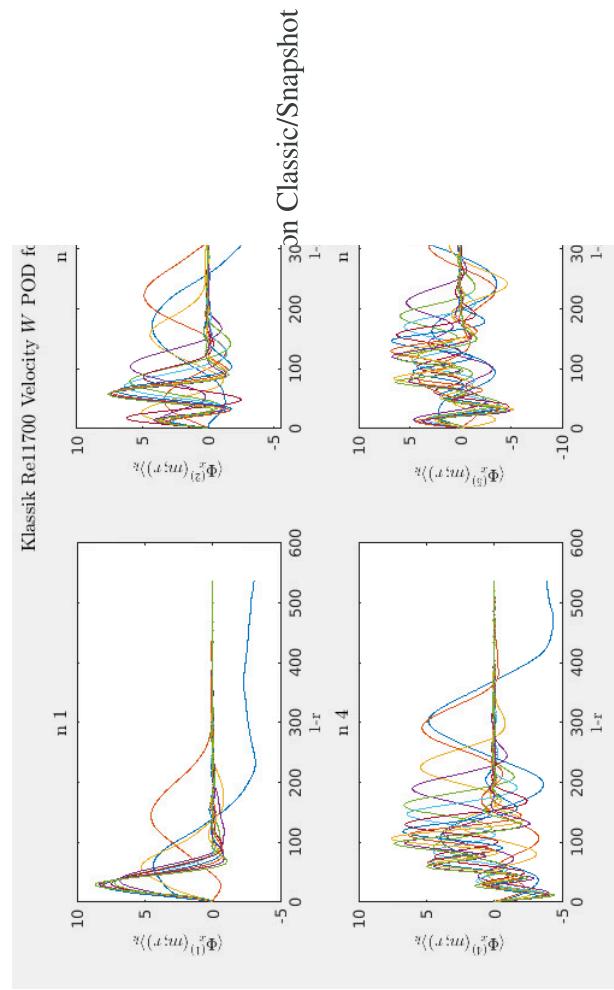
## 5. Energy r



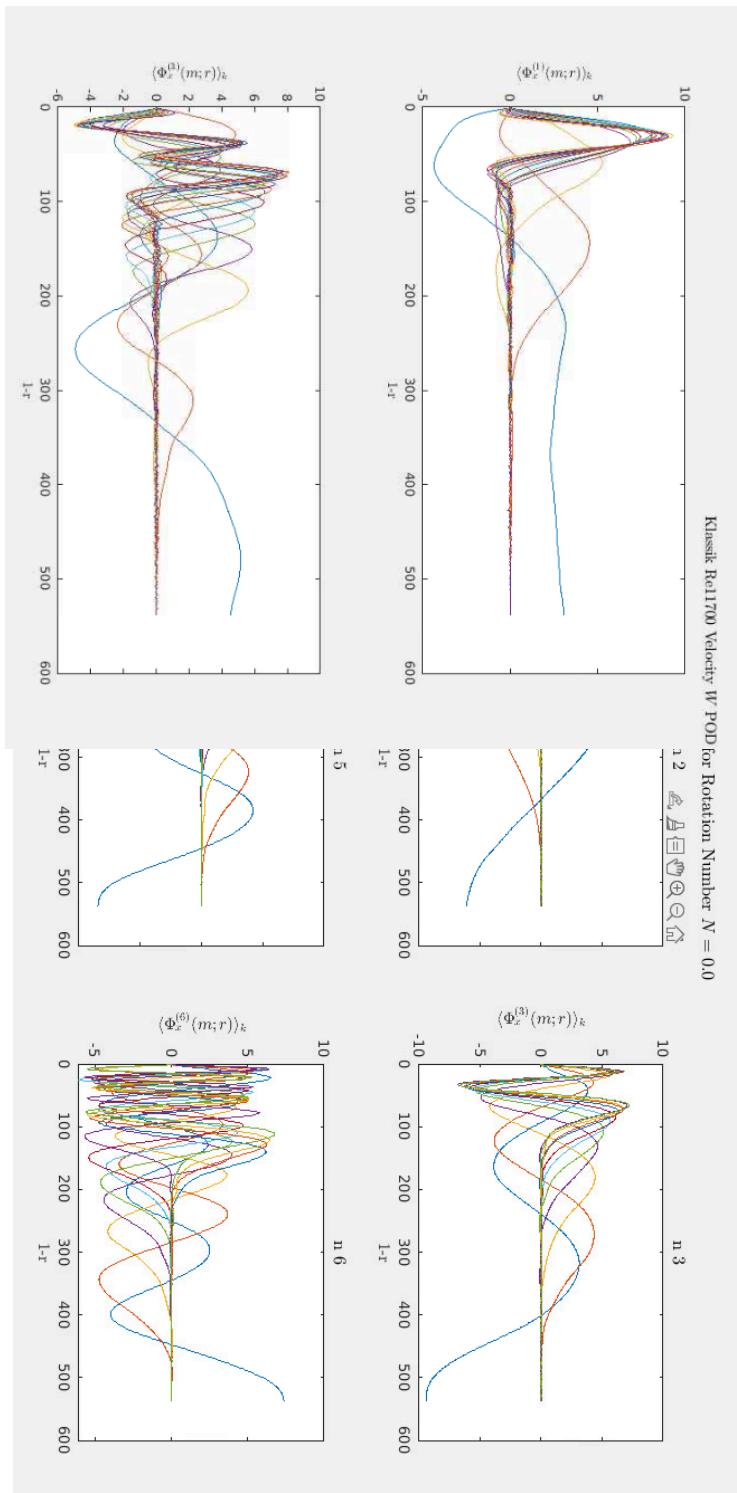
POD S=3.0



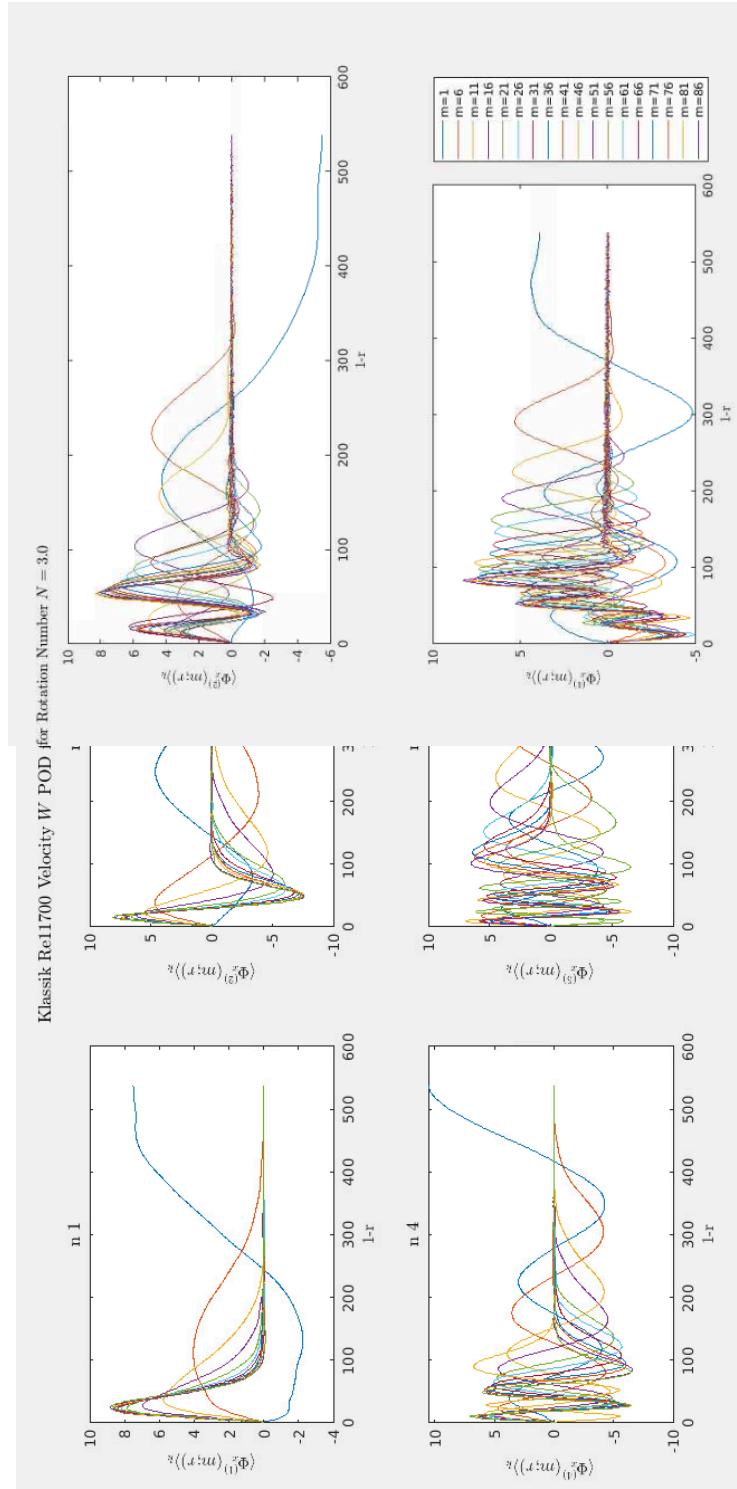
#### 4.4. Klassik



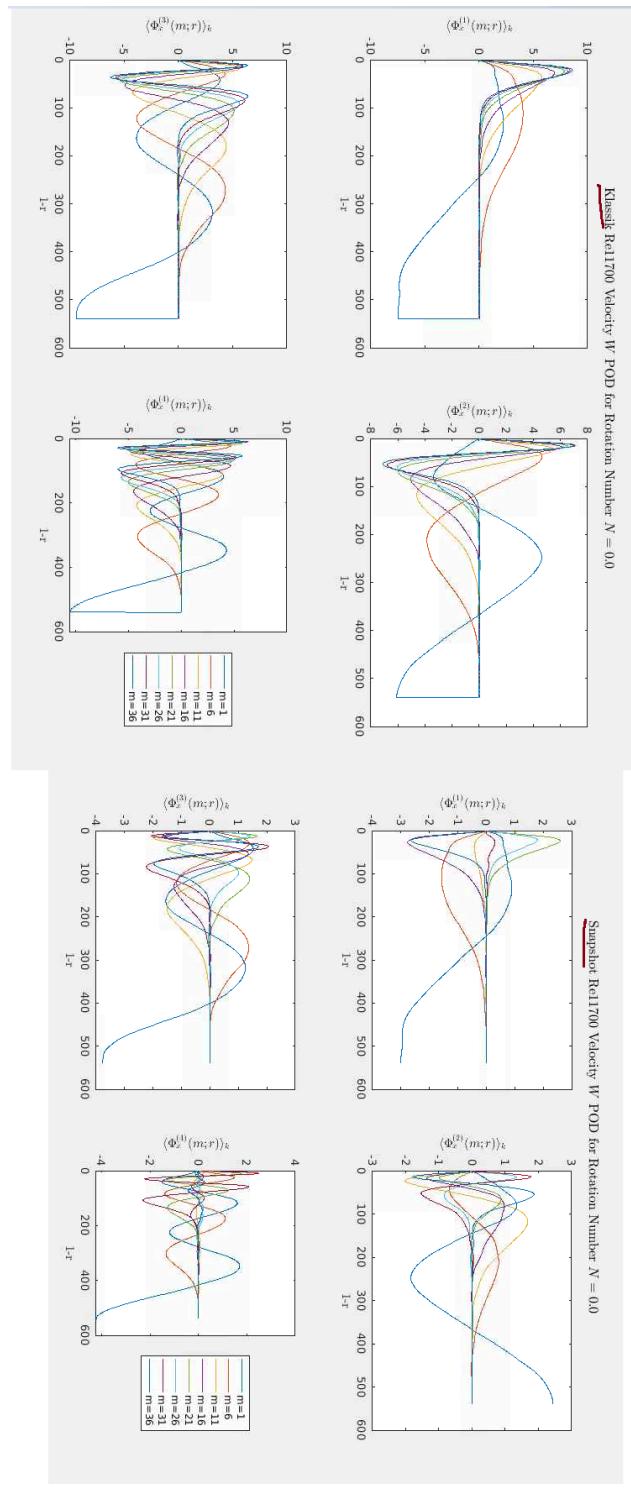
#### 4.1. Radi POD S=0.0



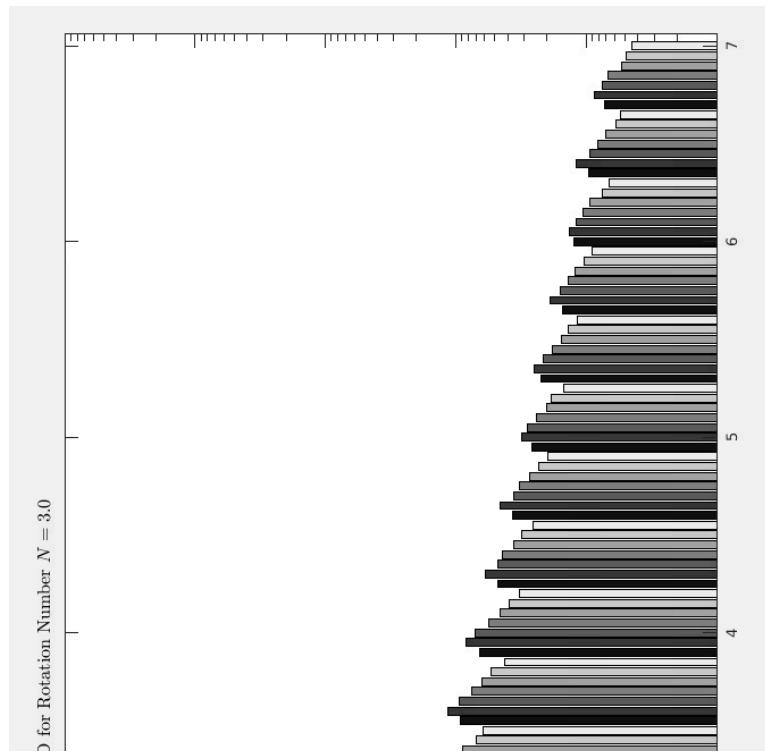
### 4.3. Klassikal Classic



## 4.2. Snapshot-Classic Comparison



; Classic



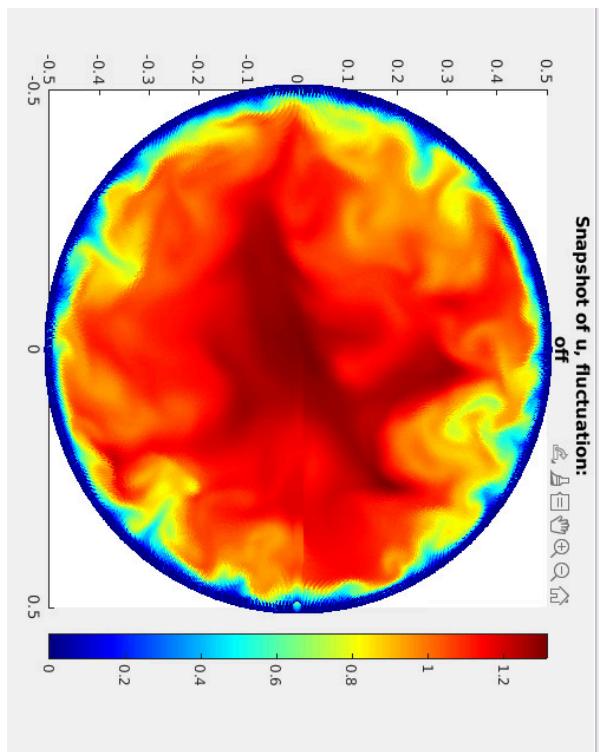


nalysis

## 6. Recon

structure

6.1. Recor



nstruction

